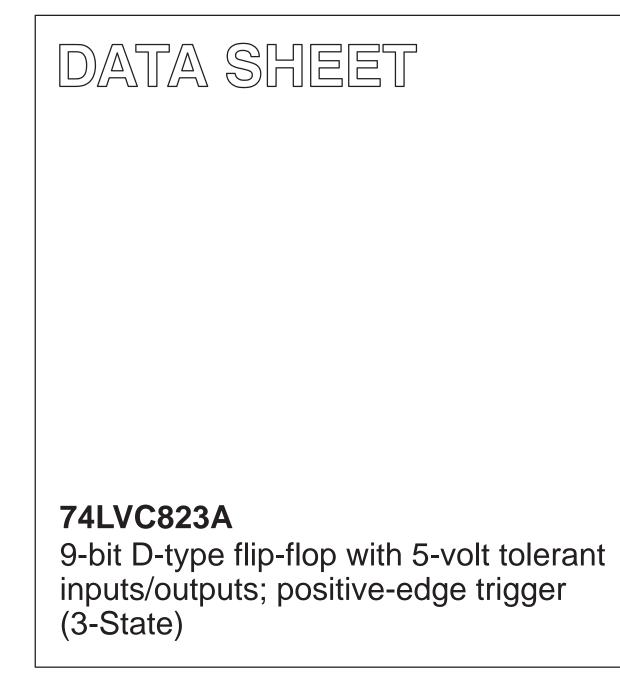
INTEGRATED CIRCUITS



Product specification

1998 Sep 24



74LVC823A

FEATURES

- 5-volt tolerant inputs/outputs, for interfacing with 5-volt logic
- Supply voltage range of 2.7V to 3.6V
- Complies with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5V
- CMOS low power consumption
- Direct interface with TTL levels
- 9-bit positive edge-triggered register
- Independent register and 3-State buffer operation
- Flow-through pin-out architecture

DESCRIPTION

The 74LVC823A is a high performance, low-power, low-voltage Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3V or 5.0V devices. In 3-state operation, outputs can handle 5V. This feature allows the use of these devices as translators in a mixed 3.3V/5V environment.

The 74LVC823A is a 9-bit D-type flip-flop with common clock (CP), Clock Enable (\overline{CE}), Master Reset (\overline{MR}) and 3-State outputs for bus-oriented applications.

The nine flip-flops will store the state of their individual D-inputs that meet the set-up and hold times requirements on the LOW-to-HIGH CP transition provided \overline{CE} is LOW. When \overline{CE} is HIGH the flip-flops hold their data.

A LOW on $\overline{\text{MR}}$ resets all flip-flops.

When \overline{OE} is LOW, the contents of the nine flip-flops is available at the outputs. When \overline{OE} is HIGH, the outputs go to the high impedance OFF-state. Operation of the \overline{OE} input does not affect the state of the flip-flops.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5 \text{ ns}$

SYMBOL	PARAMETER CONDITIONS		. PARAMETER CONDITIONS		TYPICAL	UNIT
+ /+	Propagation delay CP to Q _n	3.		ns		
t _{PHL} /t _{PLH}	Propagation delay MR to Q _n	C _L = 50 pF; V _{CC} = 3.3 V	5.2	ns		
f _{max}	Maximum clock frequency	$\begin{array}{l} C_L = 50 \text{ pF}; \\ V_{CC} = 3.3 \text{ V} \end{array}$	150	MHz		
Cl	Input capacitance		5.0	pF		
C _{PD}	Power dissipation capacitance per flip-flop	Notes 1 and 2	27	pF		

NOTES:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μ W)

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

 f_i = input frequency in MHz; C_L = output load capacity in pF;

 $f_o =$ output frequency in MHz; $V_{CC} =$ supply voltage in V;

 $\sum (C_L \times V_{CC}^2 \times f_0) =$ sum of the outputs.

2. The condition is $V_I = GND$ to V_{CC}

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	ORDERING CODE	PKG. DWG. #
24-Pin Plastic SO	-40°C to +85°C	74LVC823A D	SOT137-1
24-Pin Plastic SSOP Type II	–40°C to +85°C	74LVC823A DB	SOT340-1
24-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC823A PW	SOT355-1

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PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1	ŌĒ	Output enable input (active LOW)
2, 3, 4, 5, 6, 7, 8, 9, 10	D ₀ to D ₈	Data inputs
11	MR	Master reset (active LOW)
12	GND	Ground (0 V)
13	CP	Clock pulse (active rising)
14	CE	Clock enable (active LOW)
23, 22, 21, 20, 19, 18, 17, 16, 15	Q ₀ to Q ₈	3-State flip-flop outputs
24	V _{CC}	Positive supply voltage

FUNCTION TABLE

OPERATING MODES	INPUTS				INTERNAL FLIP-FLOPS	OUTPUTS	
OPERATING MODES	ŌĒ	MR	CE	СР	D _n	INTERNAL FLIF-FLOPS	Q ₀ to Q ₈
Clear	L	L	Х	Х	Х	L	L
Load and read register	L	H H	L L	$\stackrel{\uparrow}{\uparrow}$	l h	L H	L H
Load register and disable outputs	H H	H H	L L	X X	l h	L H	Z Z
Hold	L	Н	Н	NC	Х	NC	NC

H = HIGH voltage level

h = HIGH voltage level one set-up time prior to the LOW-to-HIGH

CP transition

= LOW voltage level L

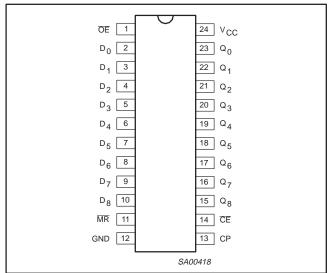
= LOW voltage level one set-up time prior to the LOW-to-HIGH Т CP transition

Z = high impedance OFF-state $\uparrow =$ LOW-to-HIGH clock transi

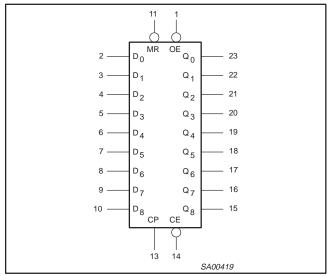
= LOW-to-HIGH clock transition

NC= no change

PIN CONFIGURATION

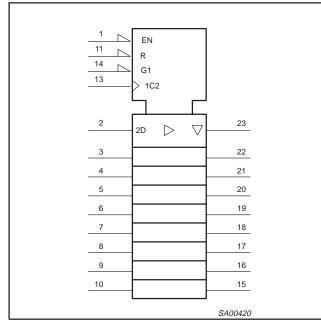


LOGIC SYMBOL

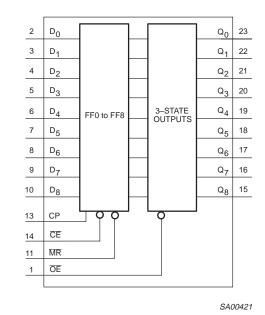


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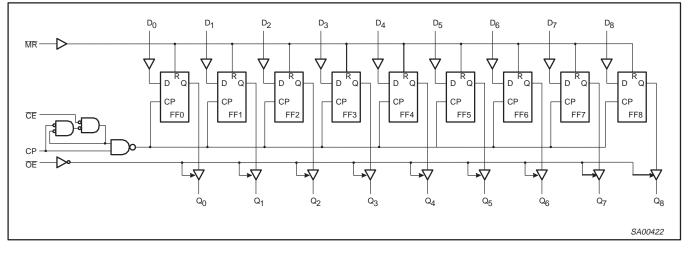
LOGIC SYMBOL (IEEE/IEC)



FUNCTIONAL DIAGRAM



LOGIC DIAGRAM



74LVC823A

RECOMMENDED OPERATING CONDITIONS

SYMBOL	DADAMETED	CONDITIONS	LIM	UNIT	
STMBUL	PARAMETER	CONDITIONS	MIN	MAX	
M	DC supply voltage (for max. speed performance)		2.7	3.6	v
V _{CC}	DC supply voltage (for low-voltage applications)		1.2	3.6	v
VI	DC Input voltage range		0	5.5	V
Vo	DC output voltage range; output HIGH or LOW state		0	V _{CC}	V
-	DC output voltage range; output 3-State		0	5.5]
T _{amb}	Operating ambient temperature range in free-air		-40	+85	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7 \text{V}$ $V_{CC} = 2.7 \text{ to } 3.6 \text{V}$	0 0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS¹

In accordance with the Absolute Maximum Rating System (IEC 134) Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +6.5	V
I _{IK}	DC input diode current	V _I <0	-50	mA
VI	DC input voltage	Note 2	-0.5 to +6.5	V
I _{OK}	DC output diode current	$V_{O} > V_{CC} \text{ or } V_{O} < 0$	±50	mA
λ/	DC output voltage; output HIGH or LOW state	Note 2	-0.5 to V _{CC} +0.5	V
Vo	DC output voltage; output 3-State	Note 2	-0.5 to 6.5	v
Ι _Ο	DC output source or sink current	$V_{O} = 0$ to V_{CC}	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		±100	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

NOTES:

 Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

			L	UNIT		
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -40°C to +85°C			
			MIN	MIN TYP ¹		1
M		V _{CC} = 1.2V	V _{CC}			v
V _{IH}	HIGH level Input voltage	V _{CC} = 2.7 to 3.6V	2.0			1 ×
M		V _{CC} = 1.2V			GND	V
V _{IL}	LOW level Input voltage	V _{CC} = 2.7 to 3.6V			0.8	1 ×
		$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -12mA$	V _{CC} -0.5			
M	HIGH level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -100 \mu A$	V _{CC} -0.2	V _{CC}		V
V _{OH}		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -18\text{mA}$	V _{CC} -0.6			
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -24\text{mA}$	V _{CC} -0.8			1
		$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 12mA$			0.40	
V _{OL}	LOW level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$			0.20	V
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 24mA$			0.55	1
ł _l	Input leakage current	$V_{CC} = 3.6V; V_1 = 5.5V \text{ or GND}$		±0.1	±5	μΑ
I _{OZ}	3-State output OFF-state current	$V_{CC} = 3.6V; V_I = V_{IH} \text{ or } V_{IL}; V_O = 5.5V \text{ or GND}$		0.1	±5	μA
I _{off}	Power off leakage supply	$V_{CC} = 0.0V; V_{I} \text{ or } V_{O} = 5.5V$		0.1	±10	μA
I _{CC}	Quiescent supply current	$V_{CC} = 3.6V; V_{I} = V_{CC} \text{ or GND}; I_{O} = 0$		0.1	10	μA
ΔI_{CC}	Additional quiescent supply current per input pin	V_{CC} = 2.7V to 3.6V; V_{I} = V_{CC} –0.6V; I_{O} = 0		5	500	μA

NOTES:

1. All typical values are at $V_{CC} = 3.3V$ and $T_{amb} = 25^{\circ}C$. 2. The specified overdrive current at the data input forces the data input to the opposite logic input state.

Product specification

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AC CHARACTERISTICS

GND = 0V; $t_r = t_f \le 2.5 \text{ns}$; $C_L = 50 \text{pF}$; $R_L = 500 \Omega$; $T_{amb} = -40^{\circ} \text{C}$ to +85°C.

			LIMITS					
SYMBOL	PARAMETER	WAVEFORM	Vc	V _{CC} = 3.3V ±0.3V			= 2.7V	UNIT
			MIN	TYP ¹	MAX	MIN	MAX	1
t _{PHL} t _{PLH}	Propagation delay CP to Q _n	Figures 1, 4	1.5	5.1	8.0	1.5	8.9	ns
t _{PHL}	Propagation delay MR to Q _n	Figures 1, 4	1.5	5.2	7.9	1.5	8.8	ns
t _{PZH} t _{PZL}	$\frac{3-\text{State output enable time}}{\overline{\text{OE}}}$ to Q_n	Figures 2, 4	1.5	5.2	7.65	1.5	8.65	ns
t _{PHZ} t _{PLZ}	3-State output disable time $\overline{\text{OE}}$ to Q_n	Figures 2, 4	1.5	3.8	6.0	1.5	7.1	ns
t _W	Clock pulse width HIGH or LOW	Figure 1	3.3			3.3		ns
t _W	Master Reset pulse width HIGH or LOW	Figure 1	3.3			3.3		ns
t _{SU}	Setup time D _n to CP	Figure 3	1.3			1.8		ns
t _{SU}	Setup time CE low before CP	Figure 3	1.8			1.0		ns
t _{rem}	Removal time MR	Figure 3	1.0			2.0	1	ns
t _h	Hold time HIGH or LOW Dn after CP	Figure 3	2.0			2.0		ns
t _h	Hold time CE LOW before CP	Figure 3	1.3			1.3		ns
f _{max}	Maximum clock pulse frequency	Figure 1	150	200		150		MHz

NOTE:

1. Unless otherwise stated, all typical values are at V_{CC} = 3.3V and T_{amb} = 25^{\circ}C.

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AC WAVEFORMS

 V_M = 1.5V at $V_{CC} \ge$ 2.7V; V_M = 0.5 V_{CC} at $V_{CC} <$ 2.7V. V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

 V_X = V_{OL} + 0.3V at V_{CC} \geq 2.7V; V_X = V_{OL} + 0.1 V_{CC} at V_{CC} < 2.7V V_Y = V_{OH} –0.3V at V_{CC} \geq 2.7V; V_Y = V_{OH} –0.1 V_{CC} at V_{CC} < 2.7V

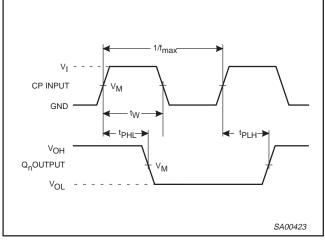


Figure 1. Clock (CP) to output (Q_n) propagation delays, the clock pulse width and the maximum clock pulse frequency.

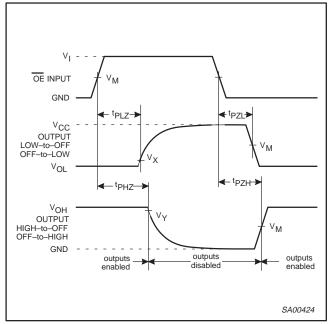


Figure 2. 3-State enable and disable times.

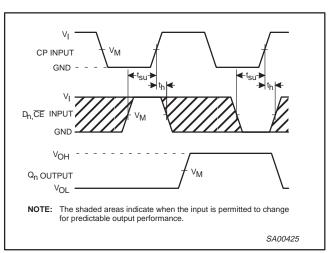


Figure 3. Data setup and hold times for the D_n input and $\overline{\text{CE}}$ input to the CP input.

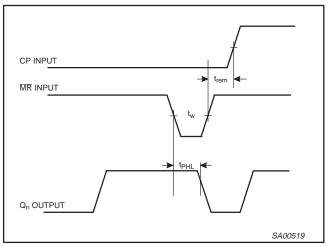


Figure 4. Master reset pulse width, master reset to clock removal time, master reset to output propagation delay.

TEST CIRCUIT

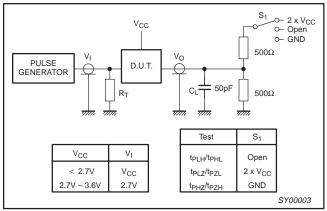
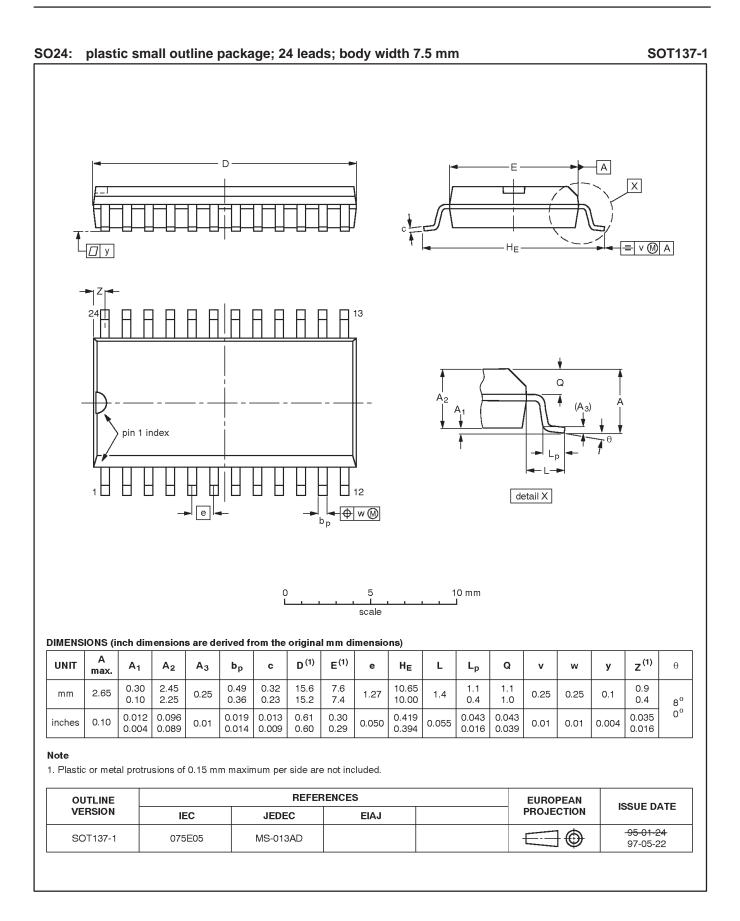
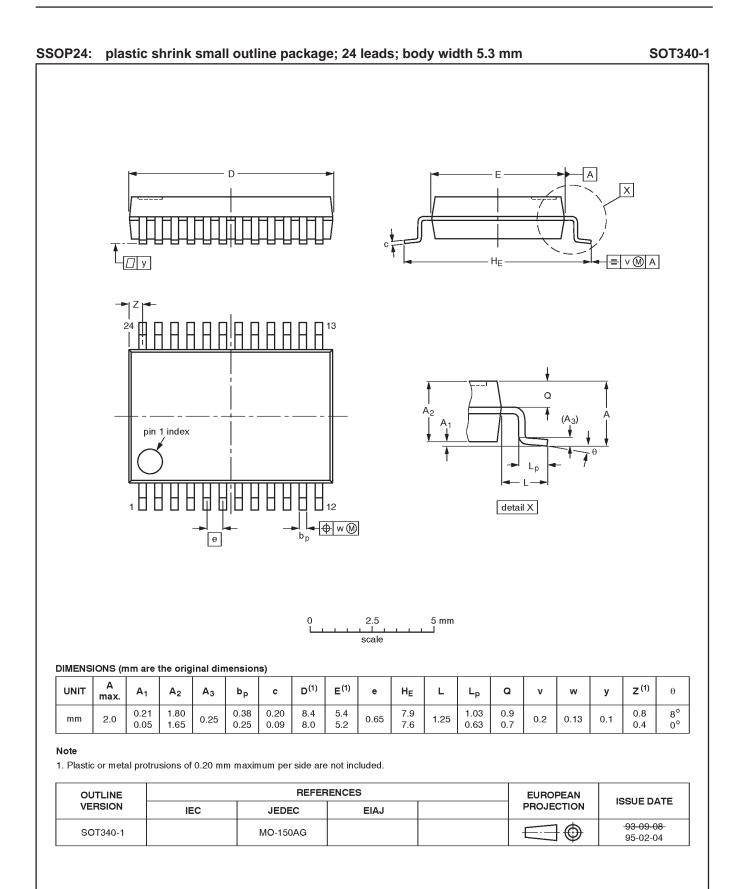


Figure 5. Load circuitry for switching times.

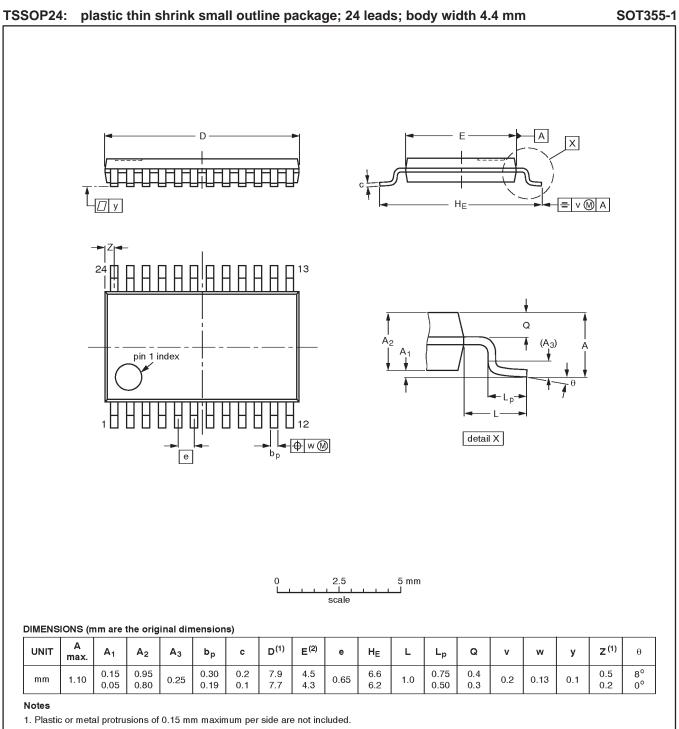
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2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFERENCES			EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1550E DATE
SOT355-1		MO-153AD				-93-06-16- 95-02-04

74LVC823A

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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